

GOLD-TIN SOLDER SUITABLE FOR SELF-ALIGNING APPLICATIONS

Abstract

- 5 A tin-rich gold-tin solder is disclosed which is particularly advantageous for self-aligning applications. When utilized with gold-plated bond locations, the out-diffusion of tin from the solder during heating functions to shift the composition of the remaining solder closer to the eutectic value, thus preserving the liquid state of the solder and improving its reflow quality with respect to conventional eutectic solders.

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